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powerful technology.

Progress in Coated Conductor at SuperPower

Drew W. Hazelton

*Low Temperature High Field Superconductor Workshop ■ LTHFSW 2010
Monterey, CA ■ 11/8/10-11/10/10*

celebrating
10 years
2000 ~ 2010

SuperPower Organization

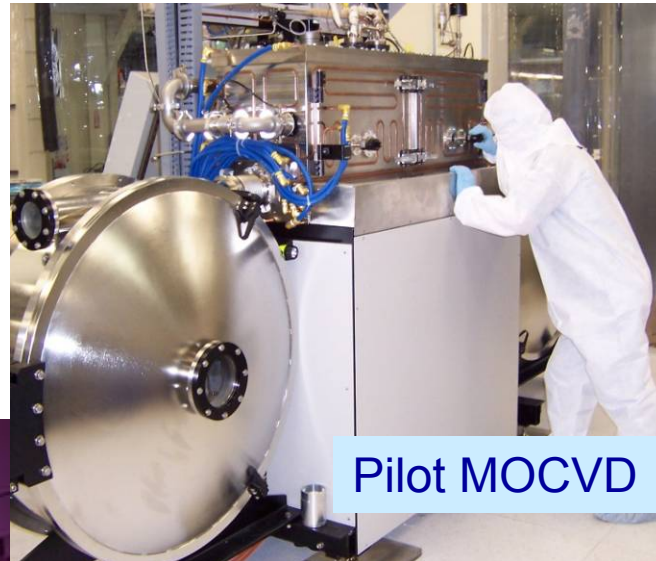
- Wholly owned subsidiary of Royal Philips Electronics, N.V.



2 Facilities –

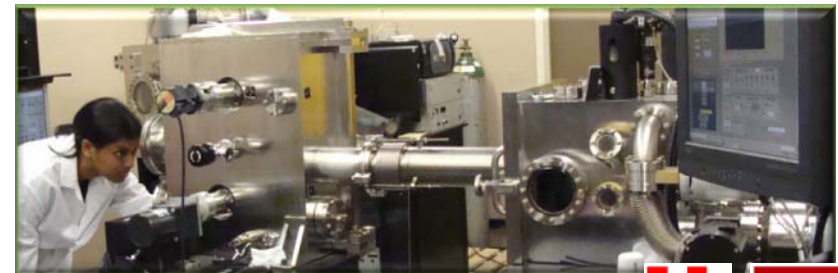
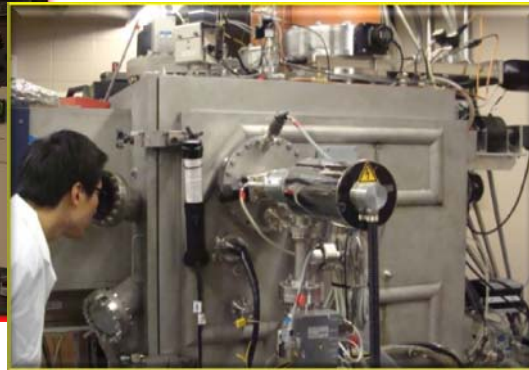
- Headquarters, manufacturing, applications – Schenectady, NY
- 2G HTS R&D – University of Houston
 - Broad scope research agreement with UH / TcSUH

2G HTS wire produced in SuperPower manufacturing facility since 2006

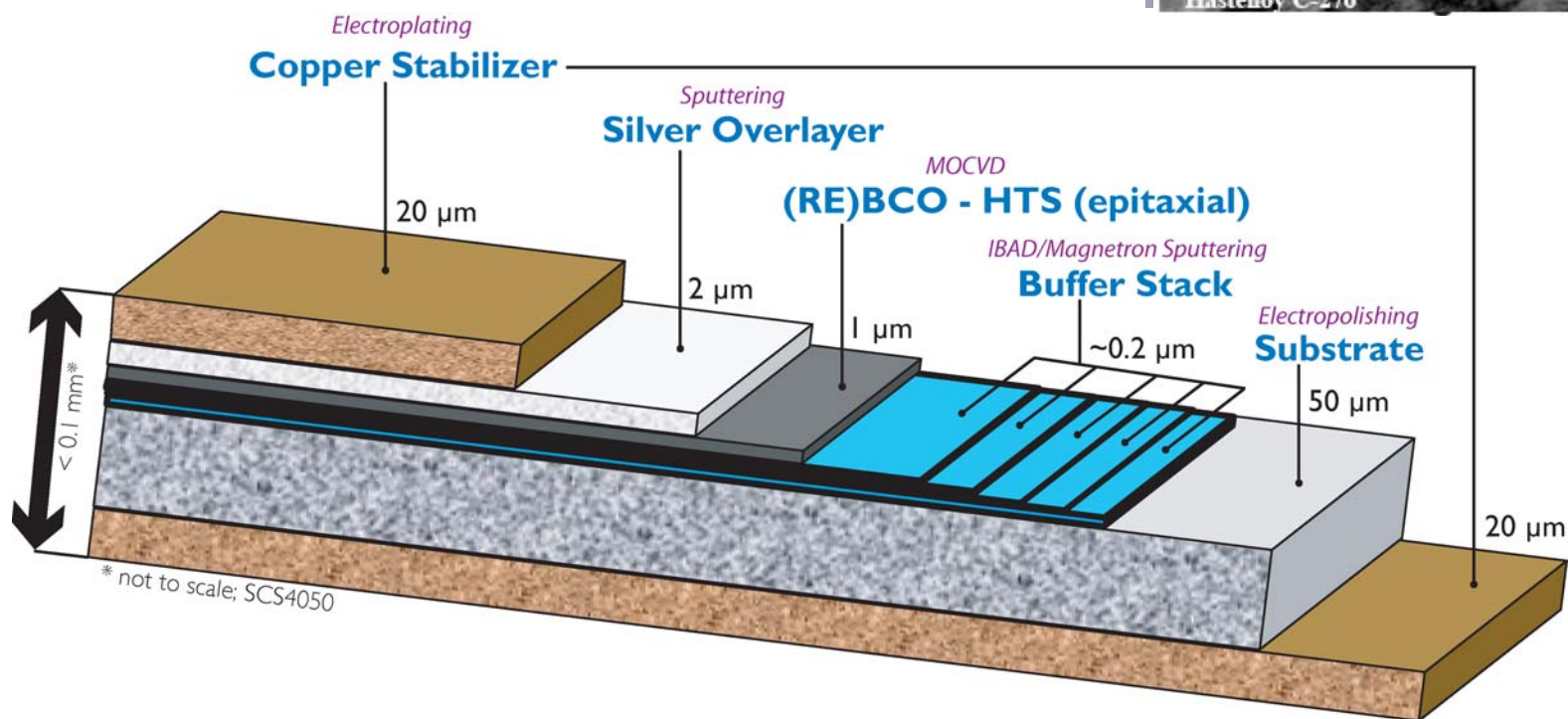
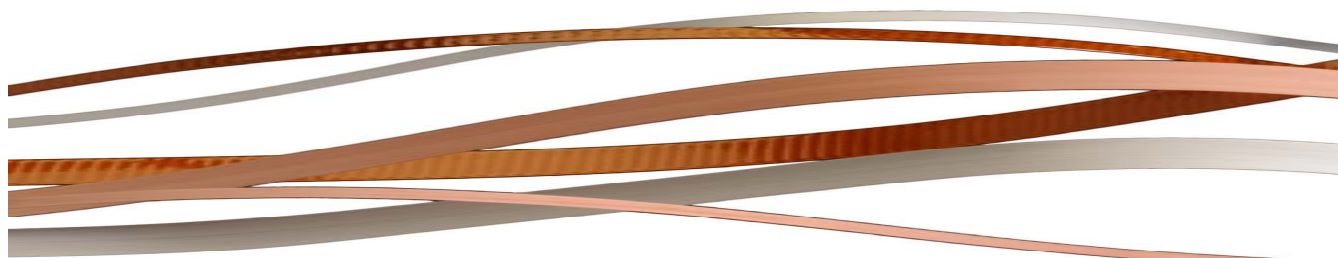


SuperPower and UH collaborate to commercialize HTS

- SuperPower has established its R&D operation at the University of Houston with 6 full-time SuperPower scientists
- All HTS research equipment located at UH
- SuperPower is establishing a Specialty Products facility at UH Research Park
- UH received \$3.5M from Texas Emerging Technology Fund to establish new facilities and add two faculty specializing in HTS devices & power engineering

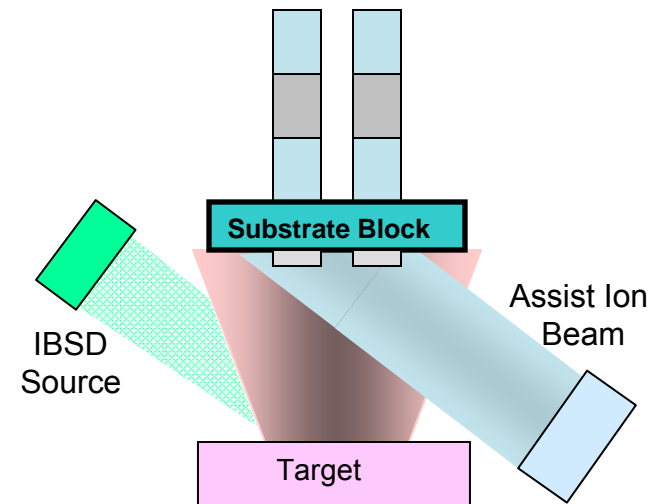


SuperPower 2G HTS Architecture



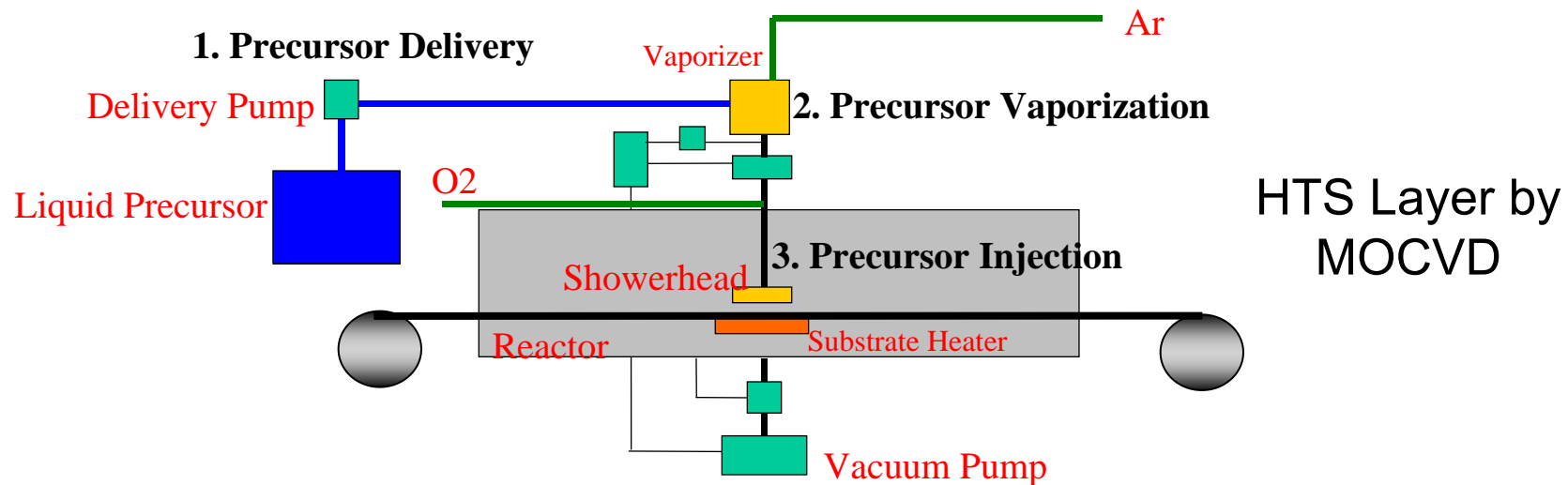
Advantages of IBAD technology

- Virtually any substrate can be used
 - *High-strength* substrates
 - *Non-magnetic* substrates
 - *Low cost, off-the shelf* substrates (Inconel, Hastelloy, Stainless Steel)
 - *Very thin* substrates (50 μm)
 - *Resistive* substrates – for low ac losses
 - *Easy to handle* – less possibility of defects
- Small grain size – sub-micron range
 - *No issues with percolation* in any length
 - Can pattern wire to *very narrow filaments for low ac loss wire*
- IBAD MgO develops excellent texture within 10 nm thickness
 - *High throughput*



Advantages of MOCVD

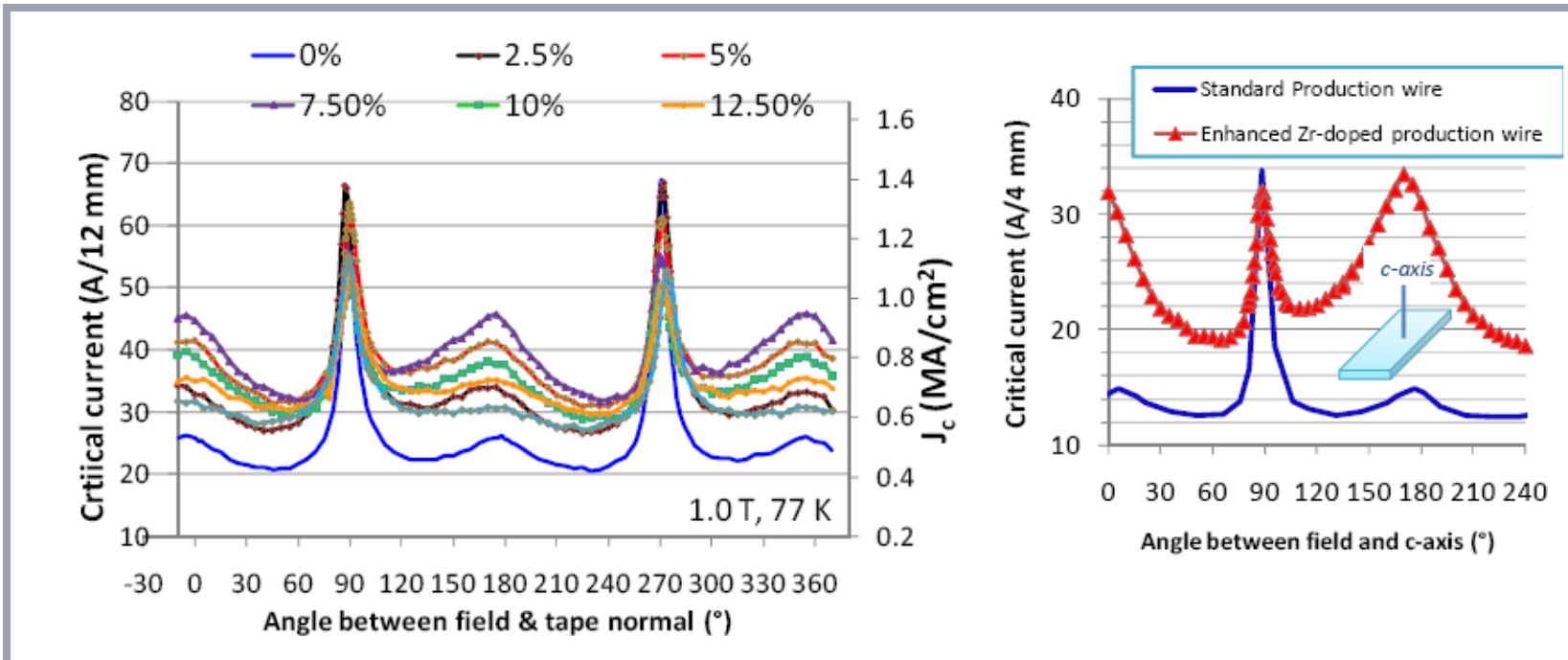
- Only process with combination of both high deposition rate & large deposition area (= highest throughput)
- Precursors are maintained outside vacuum chamber (refill is simple)
 - Solution precursor improves the reliability of vapor source supply, and makes it easy to control/adjust film composition
- Low vacuum (a few Torr)



Advantages of SuperPower 2G HTS in high field magnet applications

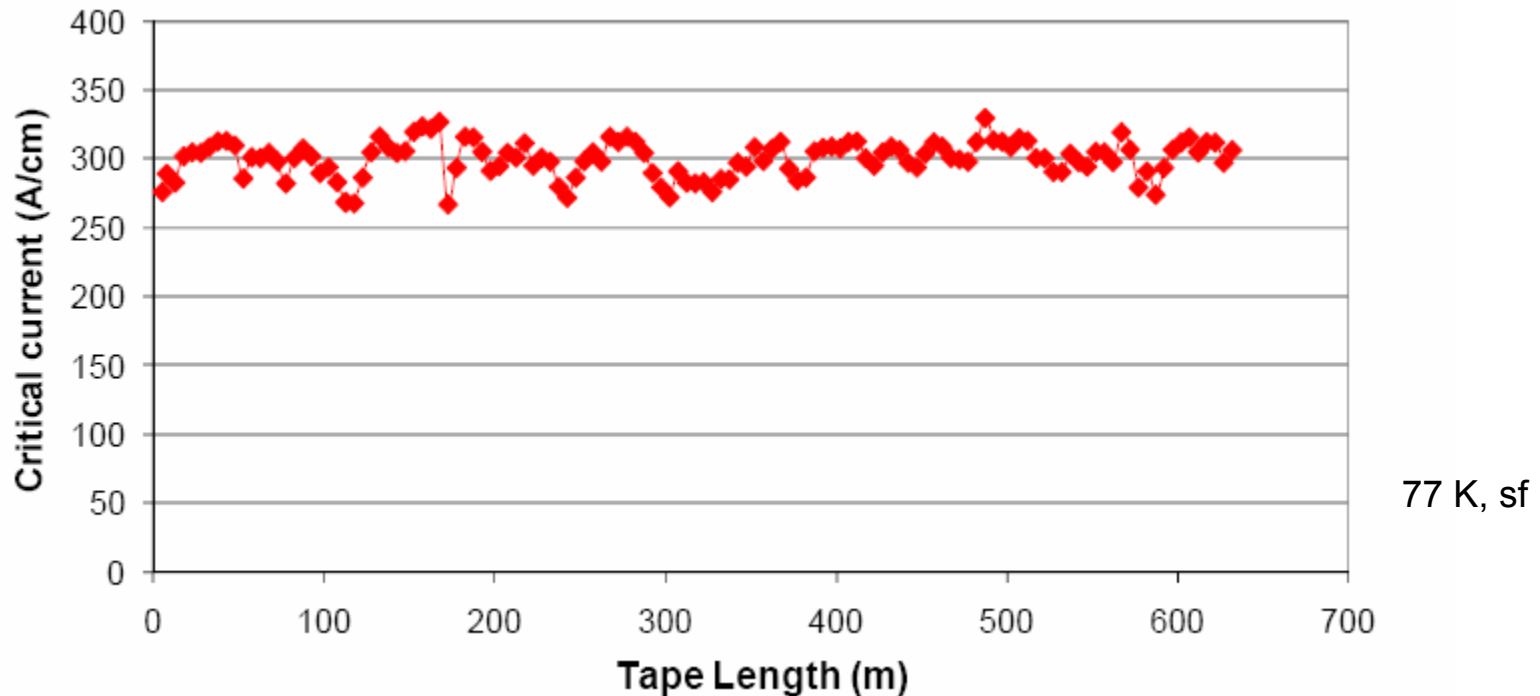
- High critical currents with excellent high field performance
 - (RE)BCO layer can be readily doped using MOCVD for added performance advantage
- High current density available in thin tape form
 - Standard thickness ~ 0.1 mm
 - (RE)BCO layer small fraction of total cross-section
- High mechanical strength
 - Strong Hastelloy® C276 substrate

Improved pinning by Zr doping of MOCVD (RE)BCO layer



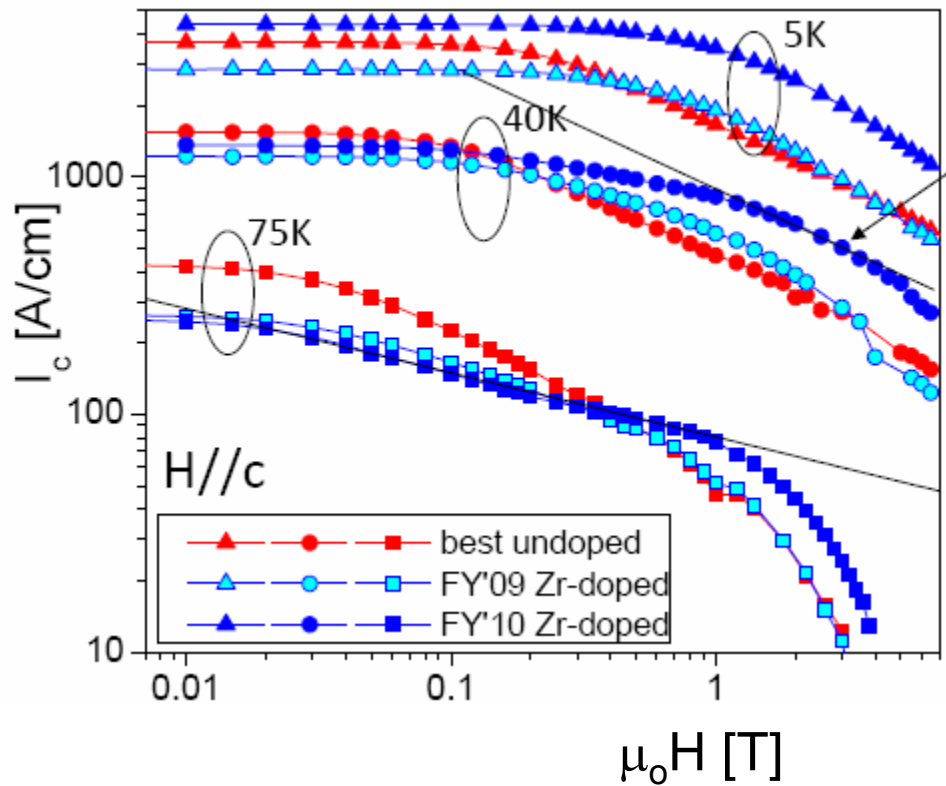
- Systematic study of improved pinning by Zr addition in MOCVD films at UH
- Process “know how” transitioned to SuperPower manufacturing

Routine manufacturing of Zr-doped tapes in long length initiated



Long tapes with Zr-doping exhibit critical currents of 250 to 300 A/cm in tapes run through the manufacturing facility

But what does the Zr-doping do at low temperatures – high fields

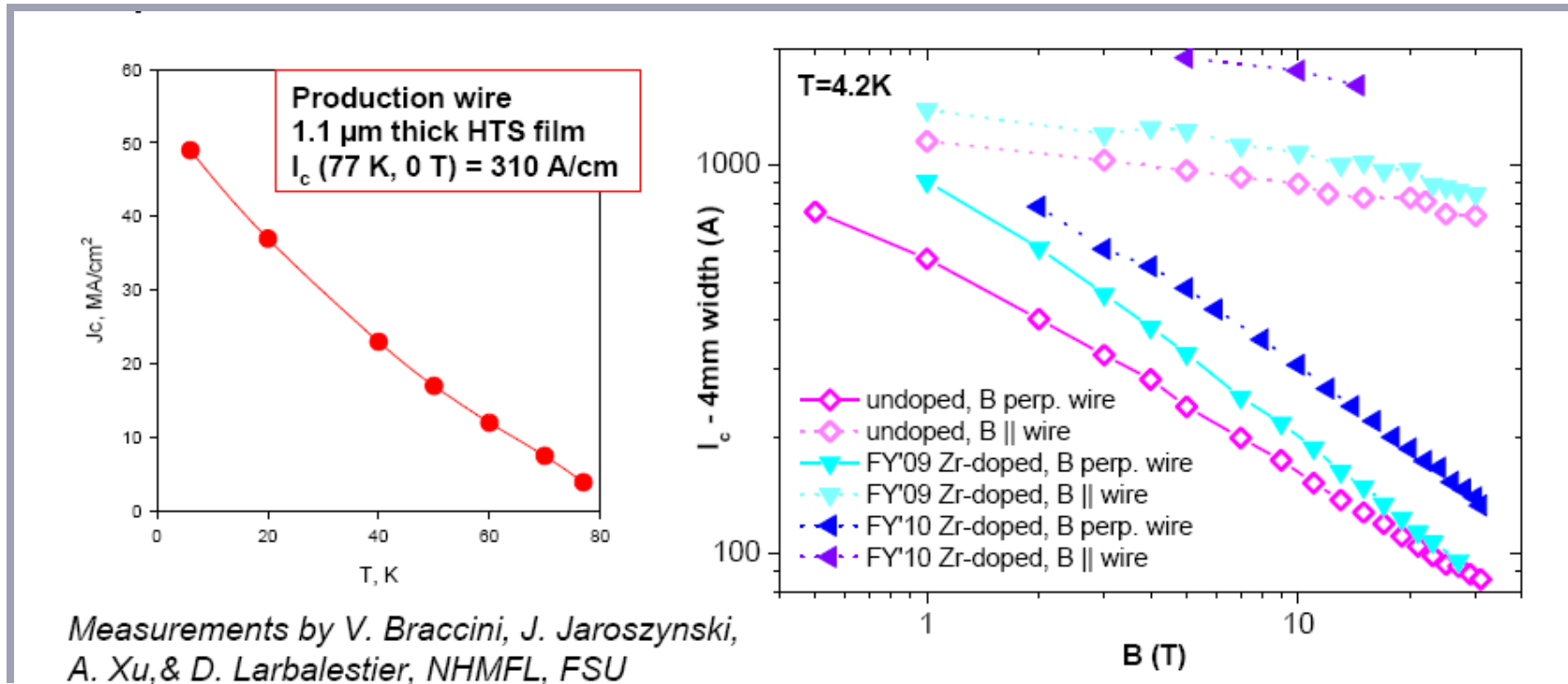


2010 Zr-doped production tapes show:

- Large I_c increase at low temperatures
- Absence of α at low T

*Measurements by B. Mairov,
L. Civale (LANL)*

Improvement extends to higher fields

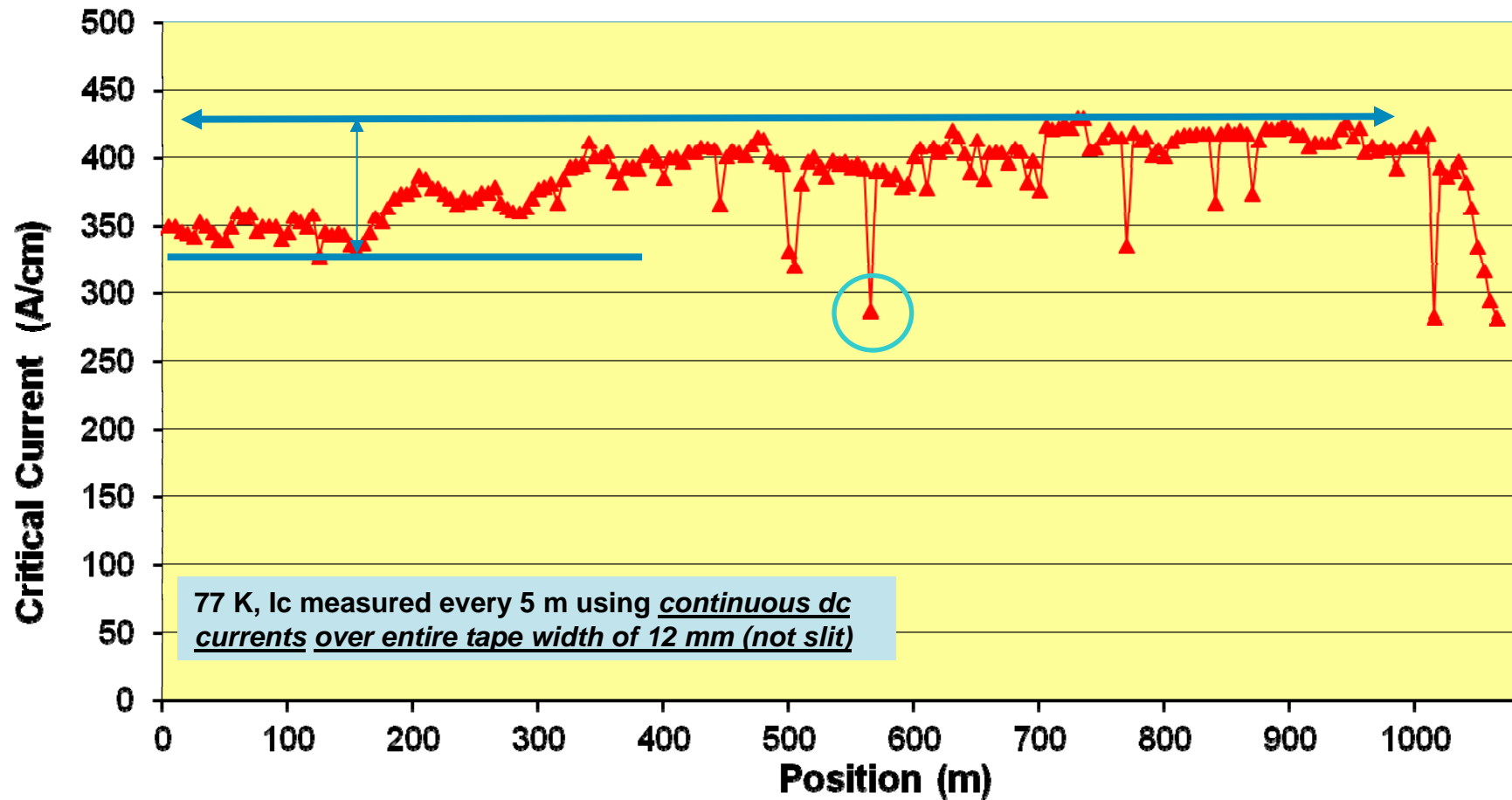


Advances with Zr-doping being locked into production

What further steps are needed for high field magnets?

- Consistent performance
- Repeatable, critical current vs. operating conditions (T, B, Bf)
- Mechanical properties
 - Axial (high strength inherent with Hastelloy substrate)
 - Transverse – more variation – multiple layers
- Joints
 - Joint resistance
 - Standard process
- Geometry control
 - Issue mainly with electroplated stabilization (dog boning)
- Amount of stabilization (copper) and quench require more understanding
- Alternative configurations: high current conductors, cables

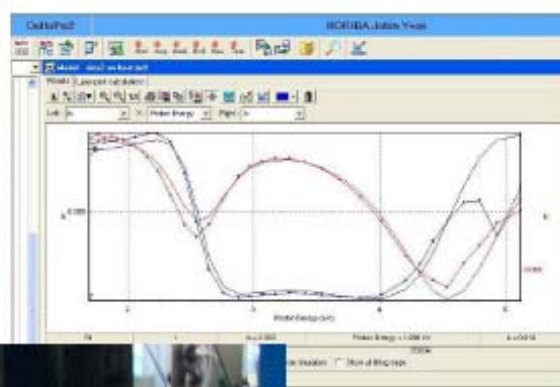
2G HTS wire production processes are routinely conducted in kilometer lengths



- Need to control I_c variability over length – MOCVD process control
- Need to understand cause of “drops” – overall process control

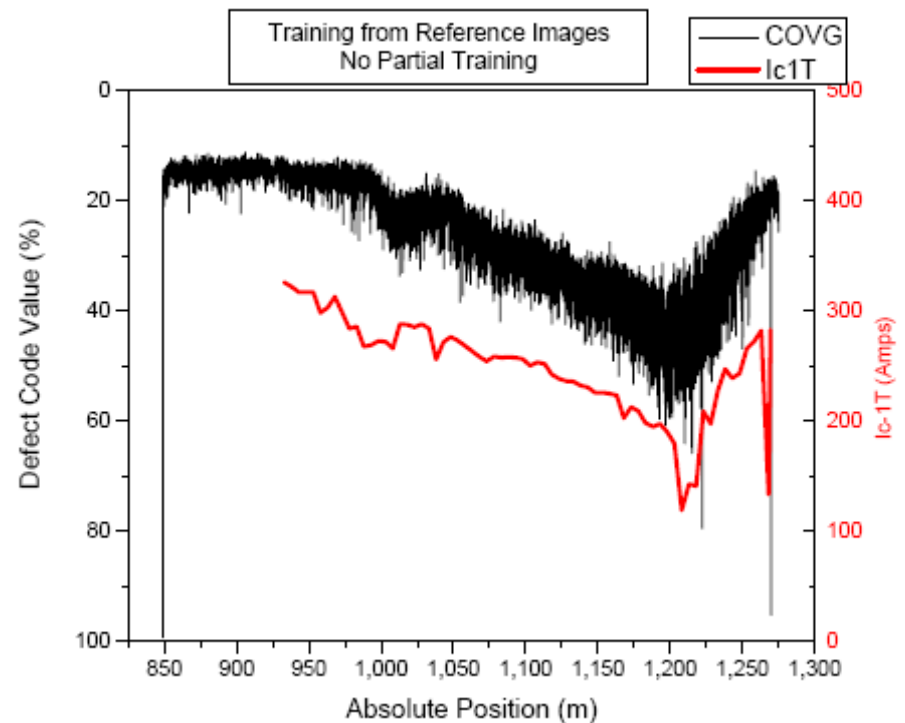
On-line ellipsometry system introduced in buffer deposition

- Thickness of alumina buffer is critical to avoid diffusion of substrate species
- New in-situ ellipsometry system installed to measure real time thickness of alumina and other buffer layers



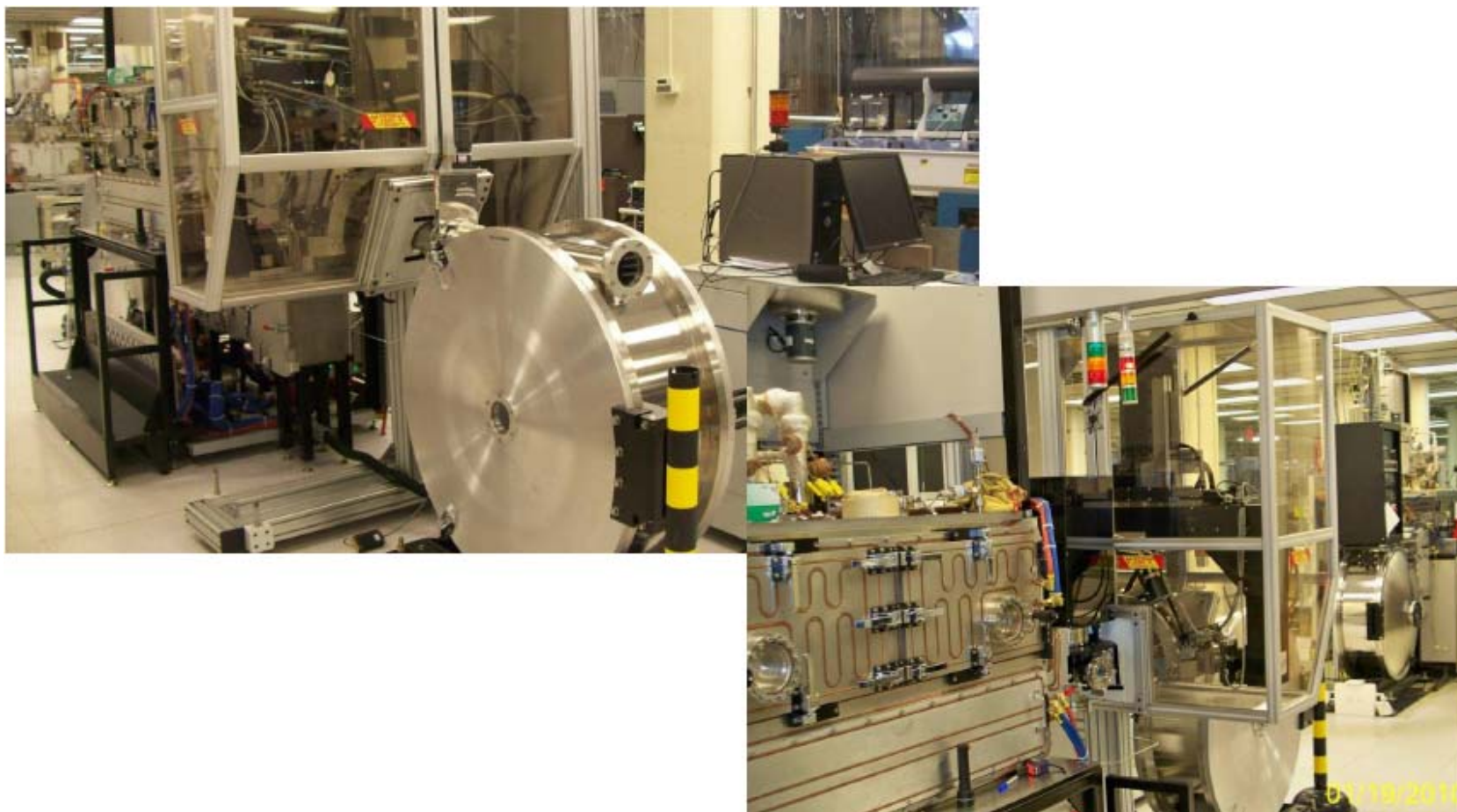
In line quality control vision system being added to improve MOCVD process feedback

- Reference images used from a previously inspected MOCVD tape with known good I_c
- Comparisons of quality maps a good predictor of critical current performance
- Process drift can be discerned in real time
- Learning how to use this data to feedback into process parameters

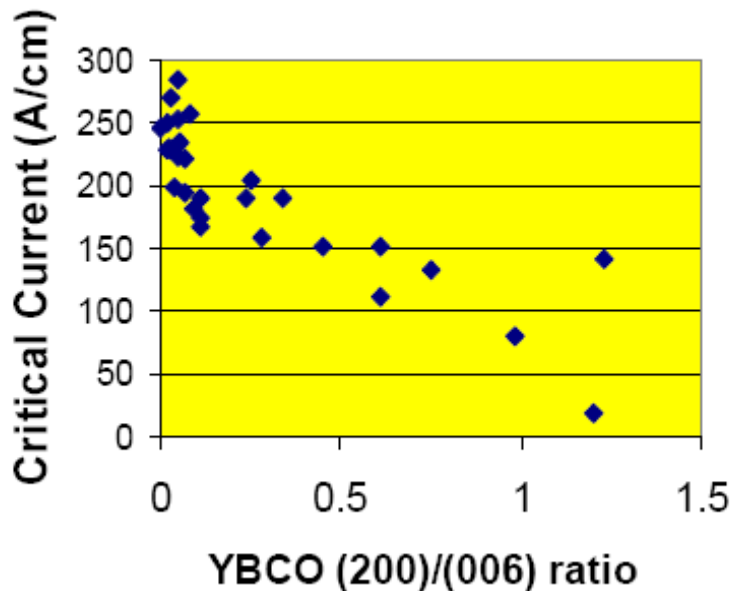
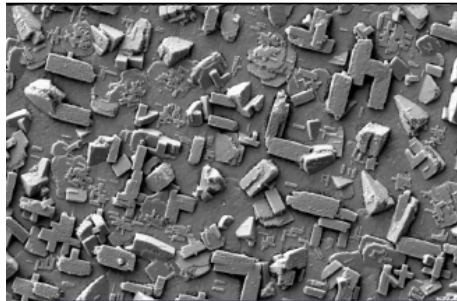


“Ic1T” refers to “first transport Ic” measurement Over the length of the conductor run

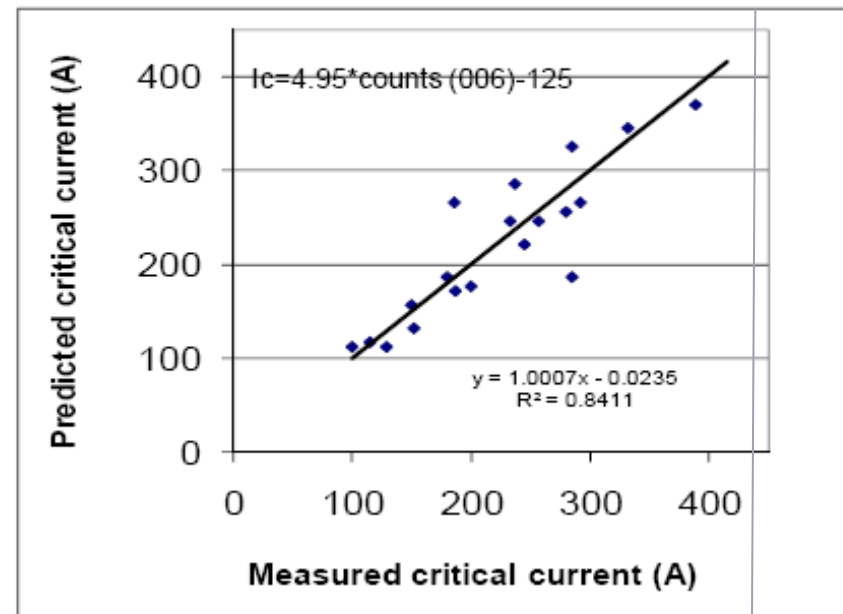
In-line XRD in new pilot-MOCVD line (M4) for real-time quality control



Early detection of a-axis growth during MOCVD is valuable in controlling 2G tape I_c

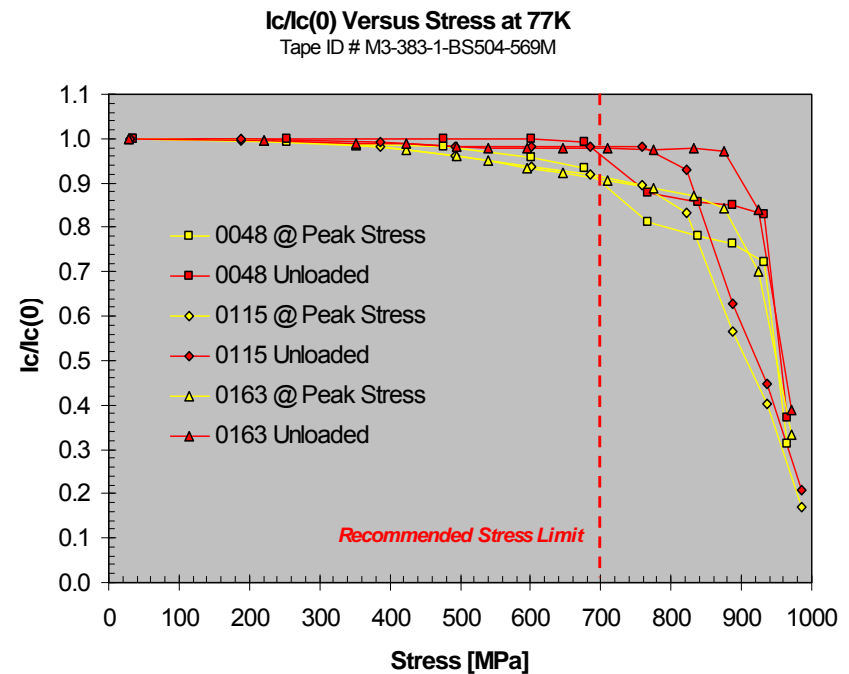


Critical current predicted based on (006) XRD peak intensity



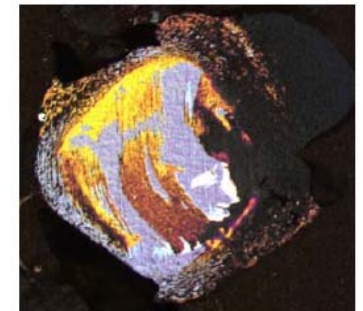
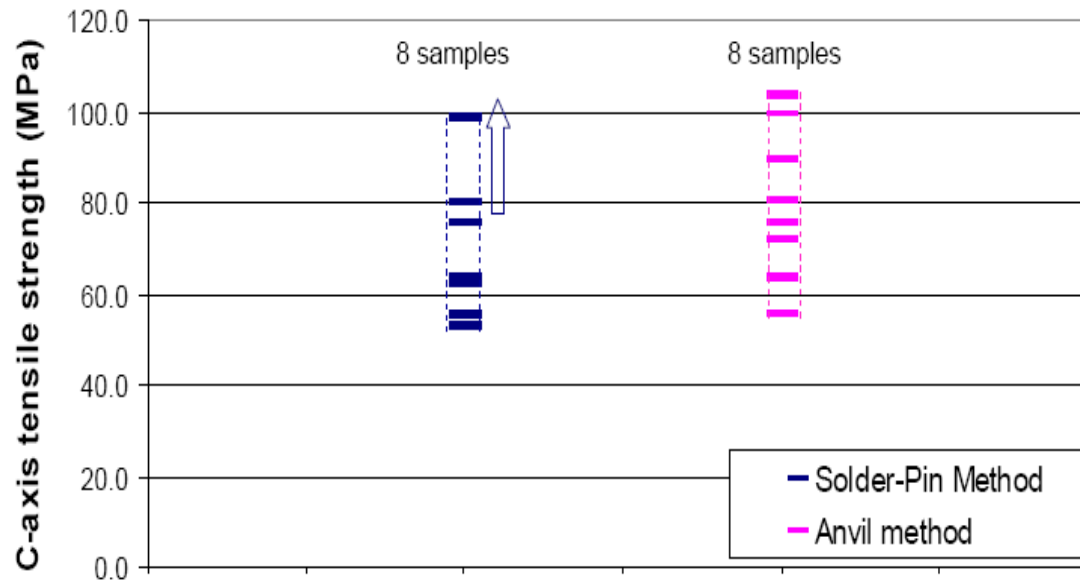
Mechanical strength very high along tape axis

Yield Stress (77K)	970 MPa (140.7 ksi) @ 0.92 % strain
Stress Limit (77K) 98% I _c reversibility 90% I _c (zero strain) at limit	700 MPa (101.5 ksi) @ ~ 0.6 % strain
Modulus (77K)	~120 GPa
Fatigue Limit (77K)	> 100,000 cycles, ~ 680 MPa tensile

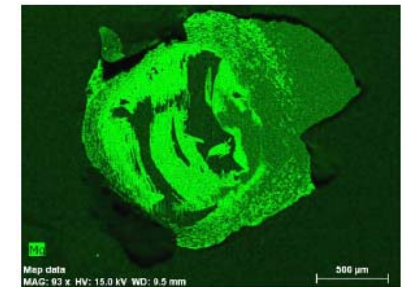


Data from Ron Holtz, NRL

C axis tensile strength evaluated by two methods



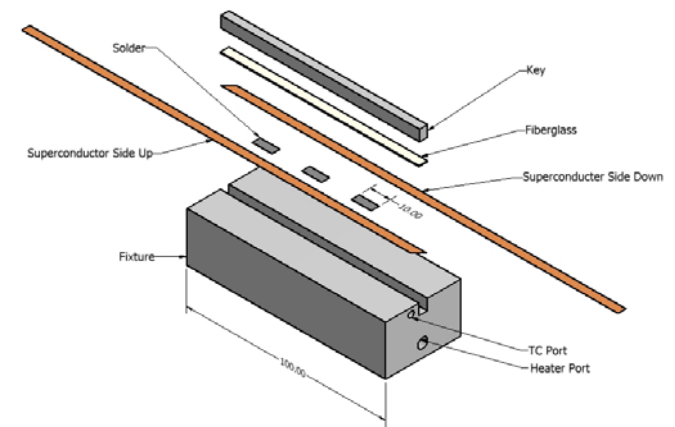
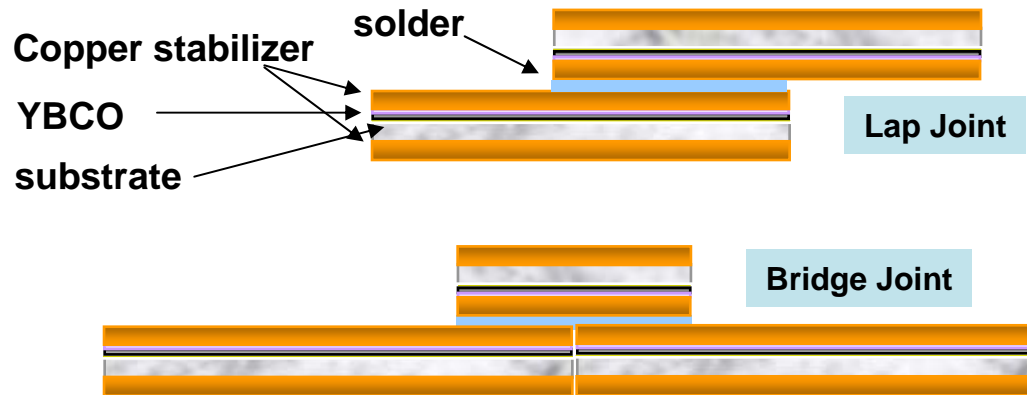
OM photo of delaminated region



EDS mapping - Mg

- Two methods of testing the c-axis tensile strength are used. Both indicate some variation in the c-axis tensile strength (test variability vs. tape variability)
- Interfaces at the debond zone are evaluated to identify the source of the variation of the c-axis tensile strength

Joint resistance - an ongoing area of development



- Fixturing developed for repeatable joint fabrication
 - Temperature control – T, duration
 - Alignment
 - Pressure during soldering step
 - Preform solder
- No degradation in I_c ($1 \mu\text{V}/\text{cm}$) over the joint or splice
- No degradation in I_c and resistance when joint or splice is bent over 25 mm diameter and thermal cycled three times
- Joint or splice resistance = **10-25 nano-ohm typical** (100 mm long overlap)
 - Variation is seen between conductor production runs
 - Variation within production runs much tighter
 - **Both variation and level of joint resistance are areas of ongoing investigation**

Summary

- 2G HTS will play a key role in pushing high field magnet technology to higher field levels
- Superior Ic performance achieved with advanced pinning techniques, including low temperature high field operating conditions
- Parallel focus areas being pursued
 - Continued performance improvements through technology developments to be introduced in a controlled manner to the commercial product
 - Manufacturing focus to provide reliable, consistent performance conductor
 - Predictable, uniform performance characteristics within and between production runs
 - In-line QC tools being put in place
 - Continued investigations to mitigate variability in
 - C-axis tensile strength
 - Joint resistance
- The need to move from a “developmental” conductor to a “manufactured” conductor is recognized



Questions?

Thank you for your interest!

For further information about SuperPower,
please visit us at: www.superpower-inc.com

or e-mail: info@superpower-inc.com